ASSOCIATION CONNECTING ELECTROMICS INDUSTRIES International and P	position De IPC, Bannockt an-American co	claration ourn, Illinois. A opyright conver	All rights reserved untions.	nder both	This docume level parts, th	ent is a declaration en declaration en	on of the substand acompasses all lo	es within the man wer level material	ufacturer liste s for which the	d item. Note: e manufacture	if the item is an as r has engineering	sembly with low responsibility.	
				Form Type Distribute					Materials and	ials and Mfg Information			
upplier Information													
ompany name*	Company un	Company unique ID			Unique ID Authority				Response Date*				
n Semiconductor									2021-02-04				
Contact Name Ti			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repre	Title - Representative			Phone - Representative*			Emai	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	·	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	MC7815	MC7815CTG ANA 1		ANA 1A 15V VREG		2021-02-04		CNC		1962.0	mg	Each	
Ianufacturing Proccess Inform	ation												
Terminal Plating / Grid Array M	minal Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		ture Max Time a	t Peak Tempe	rature Num	per of Reflow Cyc	les	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30	sec	conds 3				
omments													
or more information regarding materia	al composition	please refer to	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).								
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature	astislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.92	mg	А	Lead (Pb)	7439-92-1	7a	78.774	mg
			Supplier	Tin (Sn)	7440-31-5		4.146	mg
Lead Frame	1299.13	mg	Supplier	Iron (Fe)	7439-89-6		1.2991	mg
			Supplier	Copper (Cu)	7440-50-8		1297.4412	mg
			Supplier	Phosphorus (P)	7723-14-0		0.3897	mg
Mold Compound-Black	543.9	mg		Epoxy resin	proprietary data		38.073	mg
				Phenolic Resin	Proprietary Data		38.073	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.585	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.4495	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg